MSKSEMI 美森科













ESD

TV

TSS

MOV

GDT

PLED

2SC2881-x-MS

Product specification





NPN Silicon Epitaxial Planar Transistor

FEATURE

Power amplifier

Reference News

SOT-89



- BASE
 COLLECTOR
- B. EMITTER

MARKING

2SC2881-O-MS	2SC2881-Y-MS
CO1	CY1

Absolute Maximum Ratings (T_a= 25℃)

Parameter	Symbol	Value	Unit
Collector Base Voltage	V _{CBO}	120	V
Collector Emitter Voltage	V _{CEO}	120	V
Emitter Base Voltage	V _{EBO}	5	V
Collector Current	lc	800	mA
Base Current	l _B	160	mA
Collector Power Dissipation	Pc	0.5 1 1)	W
Junction Temperature	Tj	150	°C
Storage Temperature Range	T _{stg}	- 55 to + 150	Ô

¹⁾ Mounted on ceramic board (250 mm² X 0.8 mm).



Characteristics at T_a = 25 oC

Parameter		Symbol	Min.	Тур.	Max.	Unit
DC Current Gain at $V_{CE} = 5 \text{ V}$, $I_C = 100 \text{ mA}$ Current Gain Group	0 Y	h _{FE}	80 120	-	160 240	- -
Collector Base Cutoff Current at V _{CB} = 120 V		I _{CBO}	-	-	100	nA
Emitter Base Cutoff Current at $V_{EB} = 5 \text{ V}$		I _{EBO}	1	-	100	nA
Collector Emitter Breakdown Voltage at $I_c = 1$ mA		V _{(BR)CEO}	120	-	1	V
Emitter Base Breakdown Voltage at $I_E = 1 \text{ mA}$		$V_{(BR)EBO}$	5	-	-	V
Collector Emitter Saturation Voltage at I_c = 500 mA, I_B = 50 mA		V _{CE(sat)}	-	-	1	V
Base Emitter on Voltage at V_{CE} = 5 V, I_{C} = 500 mA		V _{BE(on)}	-	-	1	V
Transition Frequency at $V_{CE} = 5 \text{ V}$, $I_C = 100 \text{ mA}$		f⊤	-	120	-	MHz
Collector Output Capacitance at V _{CB} = 10 V, f = 1 MHz		C _{ob}	-	-	30	рF



TypicalCharacteristics

Figure 1. Static Characteristic

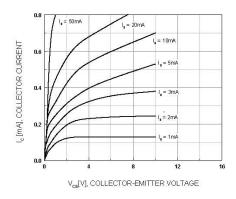


Figure 2. Base-Emitter On Voltage

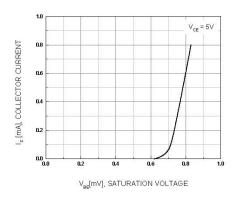


Figure 3. DC Current Gain

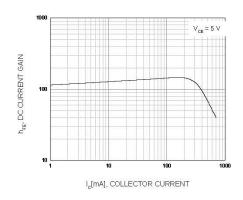


Figure 4. Collector-Emitter Saturation Voltage

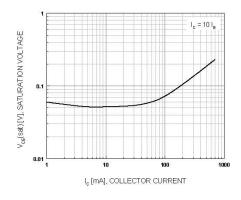
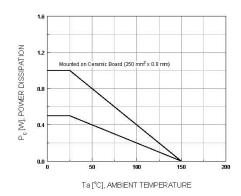
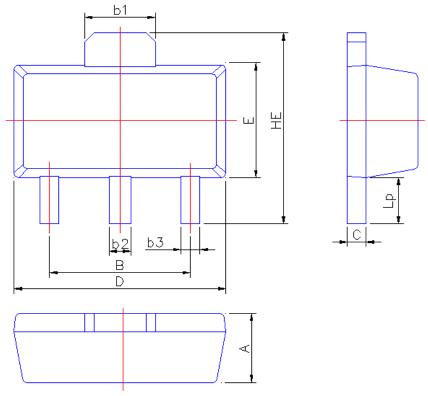


Figure 5. Power Derating





PACKAGE MECHANICAL DATA



SOT-89

	Dimension in Millimeters				
Symbol	Min	Max			
А	1.40	1.60			
В	2.95	3.05			
b1	1.45	1.70			
b2	0.45	0.60			
b3	0.35	0.50			
С	0.35	0.50			
D	4.40	4.60			
E	2.35	2.55			
HE	3.90	4.40			
Lp	0.90	1.10			

REELSPECIFICATION

P/N	PKG	QTY
2SC2881-x-MS	SOT-89	1000



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